



SamHop Microelectronics Corp.



STU/D30N15

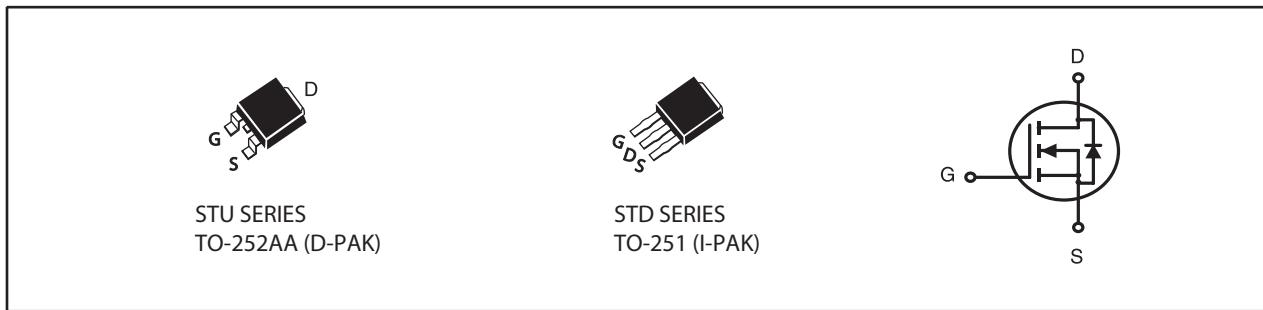
Ver 1.1

## N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Typ
150V	22A	62 @ VGS=10V

### FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- TO-252 and TO-251 Package.



### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current-Continuous	22	A
		18.4	A
$I_{DM}$	-Pulsed <sup>a</sup>	64	A
$P_D$	Maximum Power Dissipation	75	W
		52.5	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 175	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	$^\circ\text{C/W}$

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## ELECTRICAL CHARACTERISTICS (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	150			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =120V , V <sub>GS</sub> =0V			1	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2	3	4	V
R <sub>D(S)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =11A		62	72	m ohm
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =11A		28		S
<b>DYNAMIC CHARACTERISTICS</b> <sup>b</sup>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V f=1.0MHz		2387		pF
C <sub>OSS</sub>	Output Capacitance			160		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			88		pF
<b>SWITCHING CHARACTERISTICS</b> <sup>b</sup>						
t <sub>D(ON)</sub>	Turn-On Delay Time	V <sub>DD</sub> =75V I <sub>D</sub> =1A V <sub>GS</sub> =10V R <sub>GEN</sub> = 6 ohm		56		ns
t <sub>r</sub>	Rise Time			45		ns
t <sub>D(OFF)</sub>	Turn-Off Delay Time			66		ns
t <sub>f</sub>	Fall Time			17		ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =75V,I <sub>D</sub> =11A,V <sub>GS</sub> =10V		26.5		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =75V,I <sub>D</sub> =11A, V <sub>GS</sub> =10V		5.2		nC
Q <sub>gd</sub>	Gate-Drain Charge			9.1		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>S</sub> =5A		0.77	1.3	V

### Notes

a.Pulse Test:Pulse Width < 300us, Duty Cycle < 2%.

b.Guaranteed by design, not subject to production testing.

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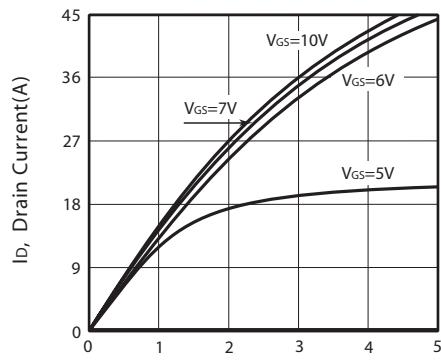


Figure 1. Output Characteristics

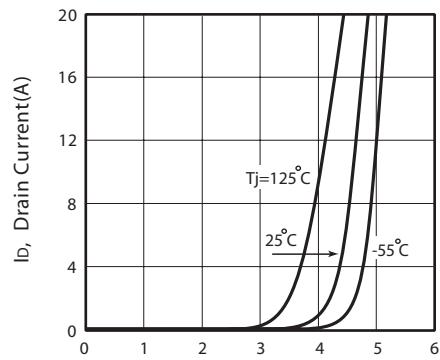


Figure 2. Transfer Characteristics

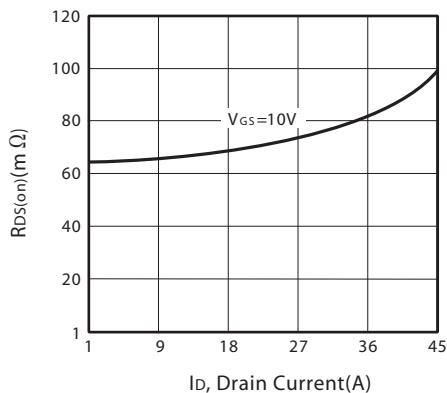


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

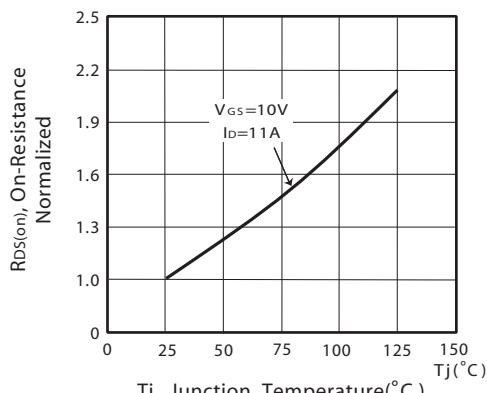


Figure 4. On-Resistance Variation with Drain Current and Temperature

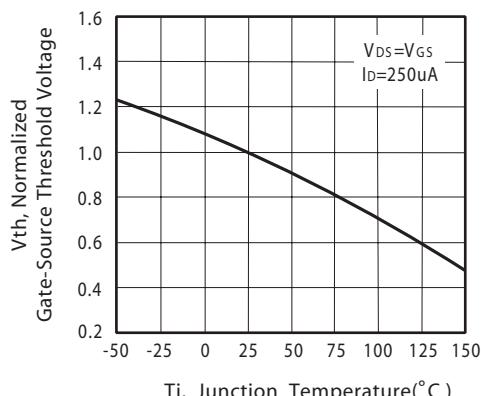


Figure 5. Gate Threshold Variation with Temperature

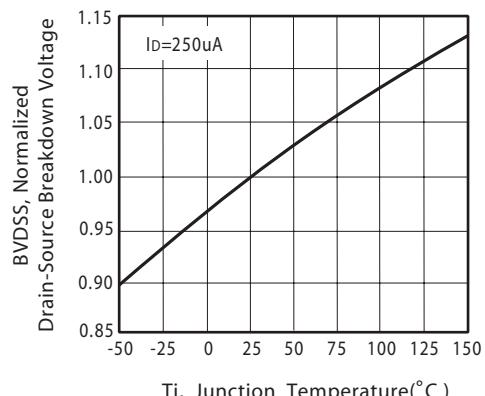
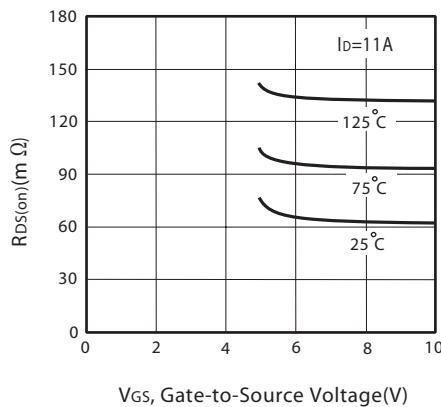


Figure 6. Breakdown Voltage Variation with Temperature

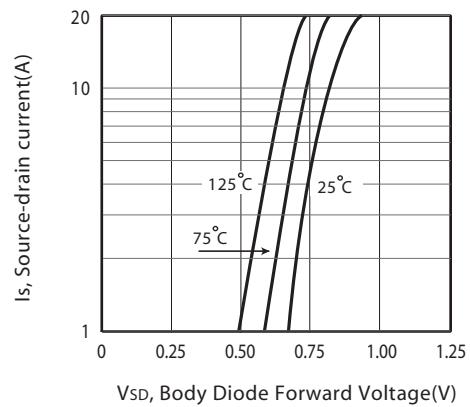
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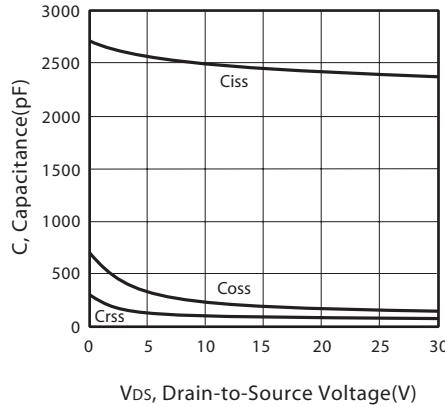
V<sub>GS</sub>, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



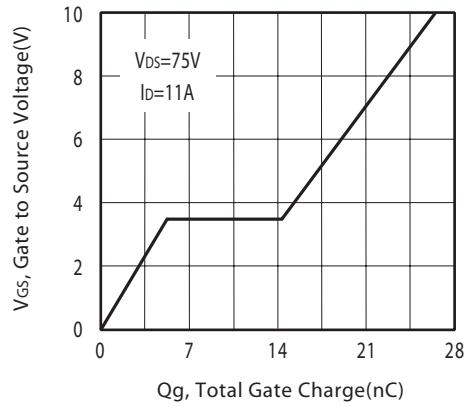
V<sub>SD</sub>, Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



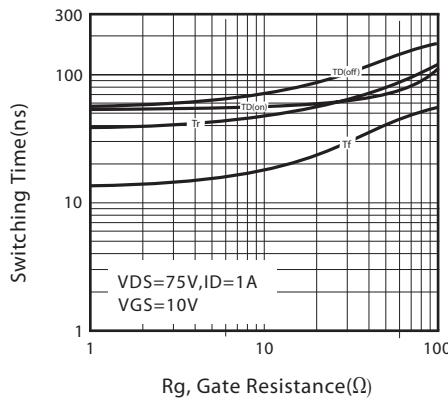
V<sub>DS</sub>, Drain-to-Source Voltage(V)

Figure 9. Capacitance



Q<sub>g</sub>, Total Gate Charge(nC)

Figure 10. Gate Charge



R<sub>g</sub>, Gate Resistance(Ω)

Figure 11. switching characteristics

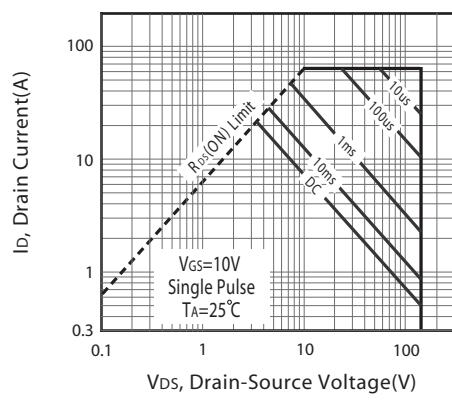
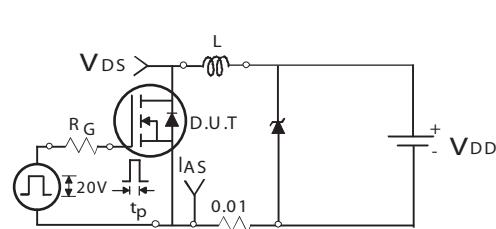


Figure 12. Maximum Safe Operating Area

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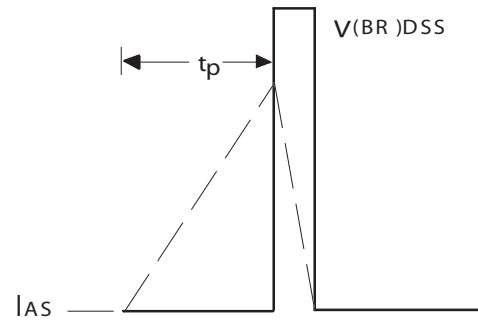
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Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

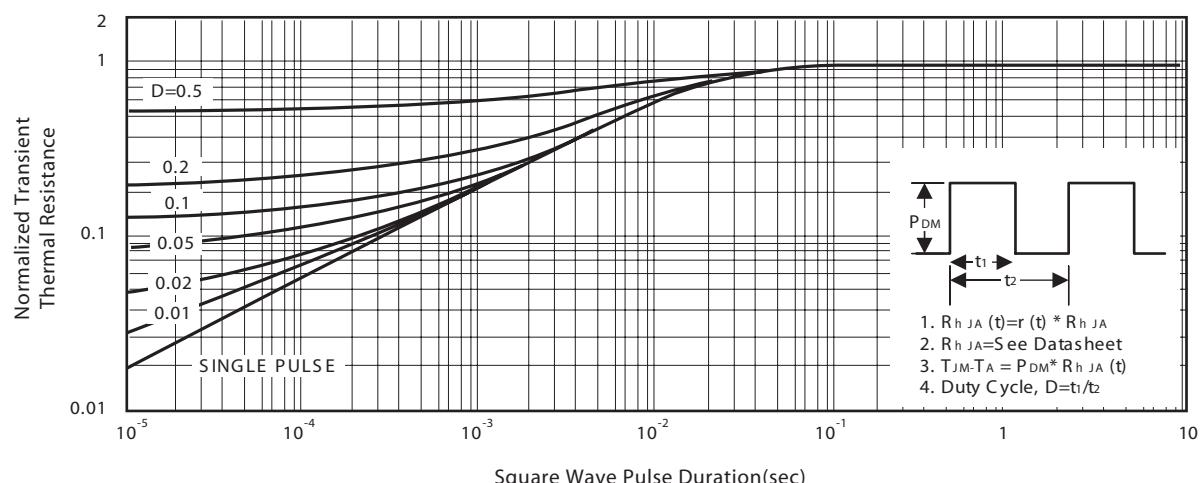


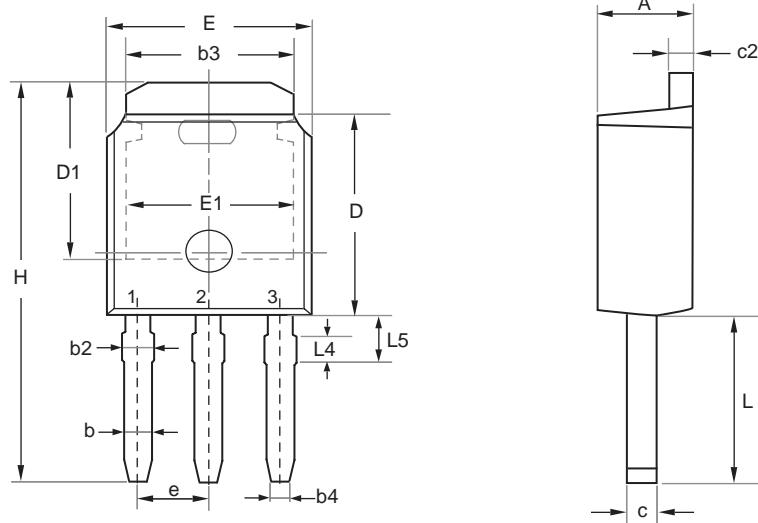
Figure 14. Normalized Thermal Transient Impedance Curve

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## PACKAGE OUTLINE DIMENSIONS

TO-251



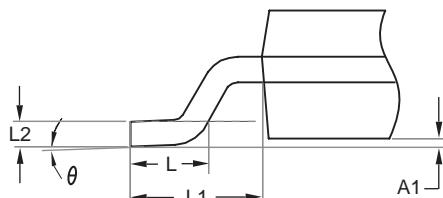
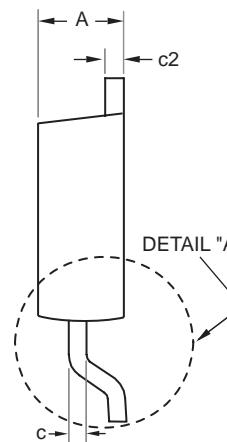
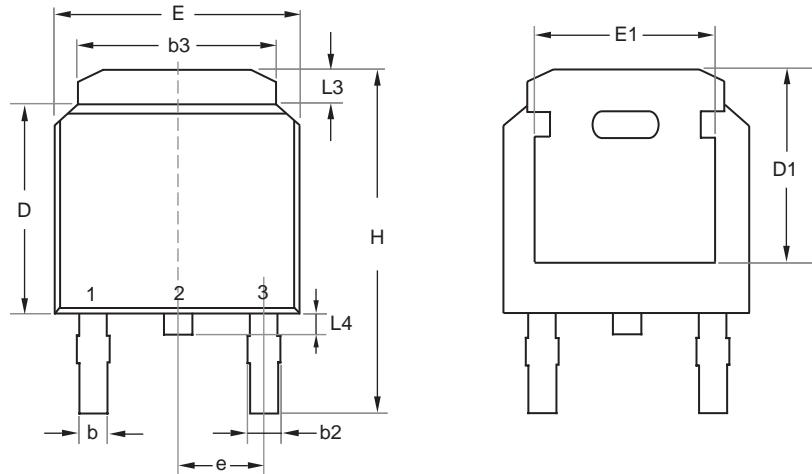
SYMBOL	MILLIMETERS	
	MIN	MAX
E	6.350	6.731
L	3.700	4.400
L4	0.698	REF
L5	0.972	1.226
D	5.970	6.223
H	9.670	11.450
b	0.630	0.850
b2	0.760	1.140
b3	4.950	5.460
b4	0.450	0.550
e	2.286	BSC
A	2.180	2.390
c	0.400	0.610
c2	0.400	0.610
D1	5.100	---
E1	4.318	---

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## TO-252



DETAIL "A"

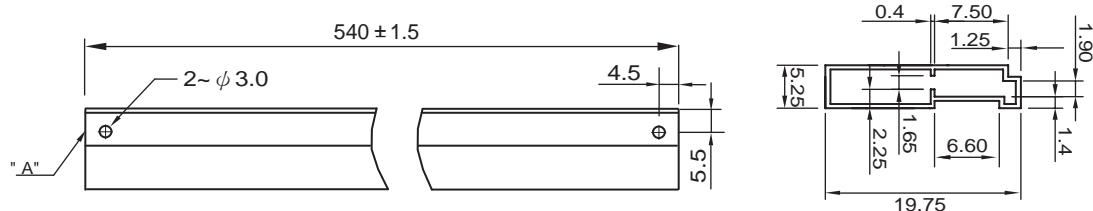
SYMBOLS	MILLIMETERS	
	MIN	MAX
A	2.200	2.380
A1	0.000	0.127
b	0.635	0.889
b2	0.762	1.143
b3	5.200	5.460
c	0.450	0.600
c2	0.450	0.580
D	6.000	6.223
D1	5.210	5.380
e	2.286 BSC	
E	6.400	6.731
E1	4.318	4.900
H	9.400	10.400
L	1.400	1.770
L1	2.743 REF	
L2	0.508 BSC	
L3	0.890	1.270
L4	0.640	1.010
$\theta$	0°	10°

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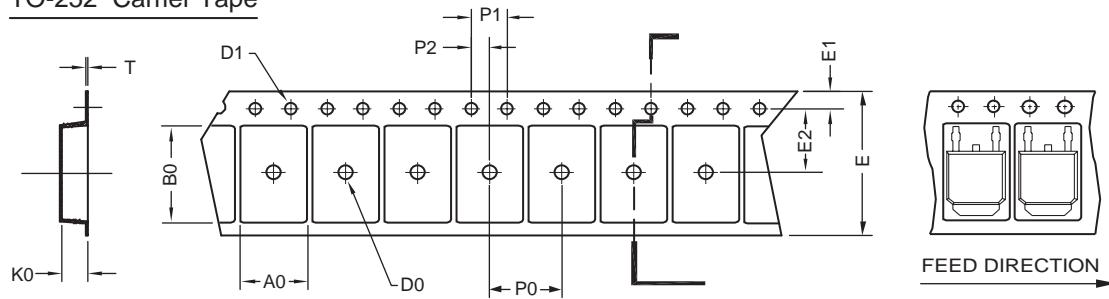
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## TO-251 Tube/TO-252 Tape and Reel Data

### TO-251 Tube



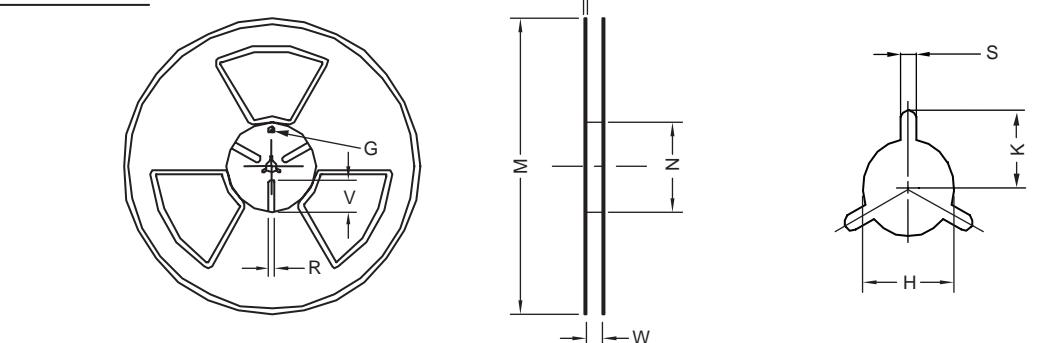
### TO-252 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
TO-252 (16 mm)	6.96 ±0.1	10.49 ±0.1	2.79 ±0.1	ψ 2	ψ 1.5 + 0.1 - 0	16.0 ±0.3	1.75 ±0.1	7.5 ±0.15	8.0 ±0.1	4.0 ±0.1	2.0 ±0.15	0.3 ±0.05

### TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	ψ 330	ψ 330 ± 0.5	ψ 97 ± 1.0	17.0 + 1.5 - 0	2.2	ψ 13.0 + 0.5 - 0.2	10.6	2.0 ± 0.5	---	---	---

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## TOP MARKING DEFINITION

TO-252

